

PATENT ASSIGNMENT

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 Stylesheet Version v1.1

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| SUBMISSION TYPE: | NEW ASSIGNMENT |
| NATURE OF CONVEYANCE: | ASSIGNMENT |
| CONVEYING PARTY DATA | |
| Name | Execution Date |
| Dae Ik KIM | 10/29/2009 |
| Jee Hyeon NA | 10/29/2009 |
| Sang Ho LEE | 10/30/2009 |
| RECEIVING PARTY DATA | |
| Name: | Electronics and Telecommunications Research Institute |
| Street Address: | 161 Gajeong-dong, Yuseong-gu |
| City: | Daejeon |
| State/Country: | REPUBLIC OF KOREA |
| Postal Code: | 305-350 |
| PROPERTY NUMBERS Total: 1 | |
| Property Type | Number |
| Application Number: | 12618836 |
| CORRESPONDENCE DATA | |
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| ATTORNEY DOCKET NUMBER: | PAX-0005-ET |
| NAME OF SUBMITTER: | JAE Y. PARK |

Total Attachments: 2
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**PATENT
 REEL: 023520 FRAME: 0292**

OP \$40.00 12618836

UNITED STATES PATENT RIGHTS, OR
UNITED STATES PLUS ALL FOREIGN PATENT RIGHTS

ASSIGNMENT

**Insert Name(s)
and Address(es)**

WHEREAS,

of Inventor(s)

Dae Ik, KIM of # 126-408 Hanbit Apt., Eoeun-dong, Yuseong-gu, Daejeon, Republic of Korea

Jee Hyeon, NA of # 108-702 Woosung Apt., Yangjae-dong, Seocho-gu, Seoul, Republic of Korea

Sang Ho, LEE of # 803-301 Daedeok Techno Valley 8-Danji Apt., Gwanpyeong-dong, Yuseong-gu, Daejeon,

Republic of Korea

(hereinafter designated as the undersigned) has (have) invented certain new and useful improvements in

**Insert Title
of Invention**

METHOD FOR EVOLVED MULTIMEDIA BROADCAST/MULTICAST SERVICE

which claims priority to [*Republic of Korea*] Application No(s). 10-2008-0130477, filed on December 19, 2008, and

for which the undersigned is (are) about to file an application for Letters Patent of the United States; and

**Insert Name
of Assignee**

WHEREAS, Electronics and Telecommunications Research Institute

**Insert Address
of Assignee**

of 161 Gajeong-dong, Yuseong-gu, Daejeon 305-350 Republic of Korea

its heirs, successors, legal representatives and assigns (hereinafter designated as the Assignee) is desirous of acquiring the entire right, title and interest in and to said invention and in and to any Letters Patent(s) that may be granted therefor in the United States of America and in any foreign countries.

NOW, THEREFORE, to all whom it may concern, be it known that, for good and valuable consideration paid to the undersigned, the receipt of which is hereby acknowledged, the undersigned has (have) sold, assigned and transferred, and by these presents does sell, assign and transfer unto the Assignee the full and exclusive right to the said invention in the United States of America, its territories, dependencies and possessions and the entire right, title and interest in and to any and all Letters Patent(s) which may be granted therefor in the United States of America, its territories, dependencies and possessions, and in any and all foreign countries;

and to any and all divisions, reissues, continuations, conversions and extensions thereof for the full term or terms for which the same may be granted.

The undersigned agree(s) to execute all papers necessary in connection with this application and any continuing, divisional, conversion or reissue applications thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

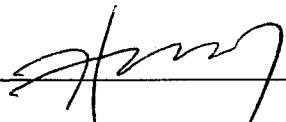
The undersigned agree (s) to execute all papers necessary in connection with any interference which may be declared concerning this application or continuation, division, conversion or reissue thereof or Letter Patent(s) or reissue patent issued thereon and to cooperate with the Assignee in every way possible in obtaining and producing evidence and proceeding with such interference.

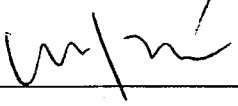
The undersigned agree(s) to execute all papers and documents and to perform any act which may be necessary in connection with claims or provisions of the International Convention for the Protection of Industrial Property or similar agreements.

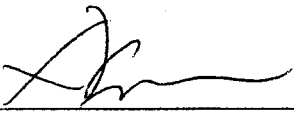
The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States of America patent(s) or a grant of a valid United States of America and any foreign patent(s) to the Assignee and to vest all rights therein hereby conveyed to said Assignee as fully and entirely as the same would have been held by the undersigned if this Assignment and sale had not been made.

The undersigned hereby authorize(s) and request(s) the Patent and Trademark Office Officials in the United States of America and in any foreign countries to issue any and all Letters Patents resulting from said application or any continuing, divisional conversion or reissue applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) the full right to convey the entire interest herein assigned, and that he has (they have) not executed, and will not execute, any agreement in conflict herewith.

The undersigned declare that all statements made herein of his own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

Name of Inventor: Dae Ik, KIM, Signature , Date 10.29.2009

Name of Inventor: Jee Hyeon, NA, Signature , Date 10.29.2009

Name of Inventor: Sang Ho, LEE, Signature , Date 10.20.2009

Name of Inventor: _____, Signature _____, Date _____

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Name of Inventor: _____, Signature _____, Date _____

Name of Inventor: _____, Signature _____, Date _____